

## TPS22968 双通道、超低电阻负载开关

### 1 特性

- 集成式双通道负载开关
- 输入电压范围：0.8V 至 5.5V
- VBIAS 电压范围：2.5V 至 5.5V
  - 非常适合 1S 电池配置
- 超低  $R_{ON}$  电阻
  - $V_{IN} = 5V$  ( $V_{BIAS} = 5V$ ) 时,  $R_{ON} = 27m\Omega$
  - $V_{IN} = 3.3V$  ( $V_{BIAS} = 5V$ ) 时,  $R_{ON} = 25m\Omega$
  - $V_{IN} = 1.8V$  ( $V_{BIAS} = 5V$ ) 时,  $R_{ON} = 25m\Omega$
- 每通道最大 4A 持续开关电流
- 低静态电流
  - $V_{BIAS} = 5V$  时为 55 $\mu A$  (两个通道)
  - $V_{BIAS} = 5V$  时为 55 $\mu A$  (单通道)
- 低控制输入阈值支持使用 1.2V、1.8V、2.5V、3.3V 逻辑
- 可配置上升时间<sup>(1)</sup>
- 快速输出放电 (QOD)<sup>(2)</sup> (可选)
- 带有散热垫的 SON 14 引脚封装
- ESD 性能经测试符合 JEDEC 标准
  - 2kV 人体放电模式 (HBM) 和 1kV 器件充电模型 (CDM)
- 闩锁性能超出 100mA, 符合 JESD 78 II 类规范的要求
- 通用输入输出 (GPIO) 使能 - 高电平有效
- TPS22968N: 仅限产品预览

(1) 有关 CT 值与上升时间之间的关系, 请参阅 [申请资料](#) 部分

(2) 此特性通过一个 270 $\Omega$  电阻器将开关的输出放电至接地 (GND), 从而防止输出悬空。

### 2 应用

- Ultrabook™
- 笔记本电脑和上网本
- 平板电脑
- 消费类电子产品
- 机顶盒
- 电信系统

### 3 说明

TPS22968x 是一款具有受控接通功能的小型、超低  $R_{ON}$  双通道负载开关。此器件包含两个可在 0.8 至 5.5V 输入电压范围内运行的 N 沟道 MOSFET, 并且每个沟道可支持最大

4A 的持续电流。每个开关由一个导通/关断输入 (ON1 和 ON2) 单独控制, 此输入可与低电压控制信号直接连接。为了能够在开关关闭时快速进行输出放电, TPS22968 中添加了一个 270 $\Omega$  的片上负载电阻器。

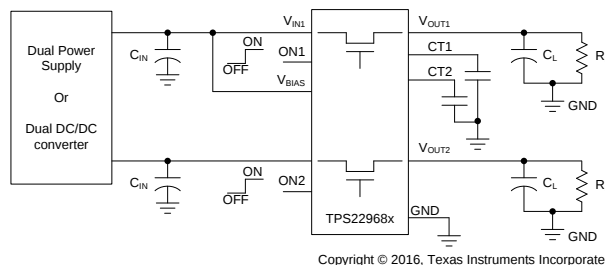
TPS22968x 采用小型、节省空间的封装 (DPU), 该封装具有集成式散热垫, 从而支持高功率耗散。该器件在自然通风环境下的额定运行温度范围为 -40 至 +105°C。

#### 器件信息<sup>(a)</sup>

| 器件型号                  | 封装        | 封装尺寸 (标称值)      |
|-----------------------|-----------|-----------------|
| TPS22968<br>TPS22968N | WSON (14) | 3.00mm x 2.00mm |

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。

典型应用电路原理图



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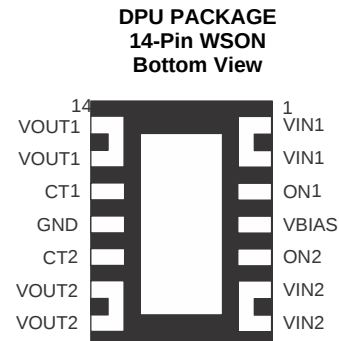
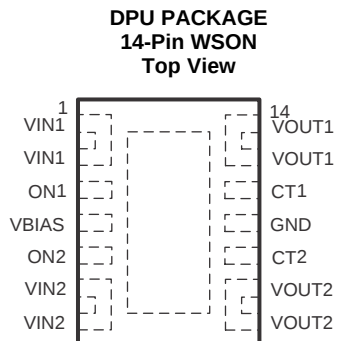
## 4 修订历史记录

|                                                                                             |             |
|---------------------------------------------------------------------------------------------|-------------|
| <b>Changes from Revision D (March 2016) to Revision E</b>                                   | <b>Page</b> |
| • 将 QOD 说明 从（仅限 TPS22968）更改成了（可选）（在特性部分中） .....                                             | 1           |
| <b>Changes from Revision E (July 2016) to Revision F</b>                                    | <b>Page</b> |
| • 已更改 <a href="#">Functional Block Diagram</a> .....                                        | 1           |
| <b>Changes from Revision C (October 2015) to Revision D</b>                                 | <b>Page</b> |
| • Made Changes to <a href="#">Thermal Considerations</a> .....                              | 22          |
| <b>Changes from Revision B (June 2015) to Revision C</b>                                    | <b>Page</b> |
| • 更新了 TPS22968N 发行版的信息。 .....                                                               | 1           |
| • Updated “TEST CONDITIONS” for RON. ....                                                   | 6           |
| • Updated “TEST CONDITIONS” for RON. ....                                                   | 7           |
| <b>Changes from Revision A (July 2014) to Revision B</b>                                    | <b>Page</b> |
| • Updated Typical Characteristics graphs. ....                                              | 8           |
| <b>Changes from Original (January 2014) to Revision A</b>                                   | <b>Page</b> |
| • 已添加 添加了处理额定值 表、特性 说明 部分、器件功能模式、应用和 实施 部分、电源相关建议 部分、布局 部分、器件和文档支持 部分以及机械、封装和可订购信息 部分 ..... | 1           |

## 5 Device Comparison

| DEVICE    | Ron (typ) at<br>VIN = 3.3 V,<br>VBIAS = 5 V | QUICK<br>OUTPUT<br>DISCHARGE | MAXIMUM<br>OUTPUT<br>CURRENT | ENABLE      |
|-----------|---------------------------------------------|------------------------------|------------------------------|-------------|
| TPS22968  | 25 mΩ                                       | Yes                          | 4 A                          | Active High |
| TPS22968N | 25 mΩ                                       | No                           | 4 A                          | Active High |

## 6 Pin Configuration and Functions



### Pin Functions

| PIN |             | I/O | DESCRIPTION                                                                                                                                                     |
|-----|-------------|-----|-----------------------------------------------------------------------------------------------------------------------------------------------------------------|
| NO. | NAME        |     |                                                                                                                                                                 |
| 1   | VIN1        | I   | Switch 1 input. Bypass this input with a ceramic capacitor to GND                                                                                               |
| 2   |             |     |                                                                                                                                                                 |
| 3   | ON1         | I   | Active-high switch 1 control input. Do not leave floating                                                                                                       |
| 4   | VBIAS       | I   | Bias voltage. Power supply to the device. Recommended voltage range for this pin is 2.5 V to 5.5 V. See the <a href="#">VIN and VBIAS Voltage Range</a> section |
| 5   | ON2         | I   | Active-high switch 2 control input. Do not leave floating                                                                                                       |
| 6   | VIN2        | I   | Switch 2 input. Bypass this input with a ceramic capacitor to GND                                                                                               |
| 7   |             |     |                                                                                                                                                                 |
| 8   | VOUT2       | O   | Switch 2 output                                                                                                                                                 |
| 9   |             |     |                                                                                                                                                                 |
| 10  | CT2         | O   | Switch 2 slew rate control. Can be left floating                                                                                                                |
| 11  | GND         | —   | Ground                                                                                                                                                          |
| 12  | CT1         | O   | Switch 1 slew rate control. Can be left floating                                                                                                                |
| 13  | VOUT1       | O   | Switch 2 output                                                                                                                                                 |
| 14  |             |     |                                                                                                                                                                 |
| 15  | Thermal Pad | —   | Thermal pad (exposed center pad) to alleviate thermal stress. Tie to GND. See the <a href="#">Application Information</a> section for layout guidelines         |

## 7 Specifications

### 7.1 Absolute Maximum Ratings

Over operating free-air temperature (unless otherwise noted)<sup>(1)</sup>

|                     |                                                                       | MIN  | MAX | UNIT <sup>(2)</sup> |
|---------------------|-----------------------------------------------------------------------|------|-----|---------------------|
| V <sub>IN1,2</sub>  | Input voltage                                                         | −0.3 | 6   | V                   |
| V <sub>BIAS</sub>   | Bias voltage                                                          | −0.3 | 6   | V                   |
| V <sub>OUT1,2</sub> | Output voltage                                                        | −0.3 | 6   | V                   |
| V <sub>ON1,2</sub>  | ON voltage                                                            | −0.3 | 6   | V                   |
| I <sub>MAX</sub>    | Maximum continuous switch current per channel, T <sub>A</sub> = 30 °C |      | 4   | A                   |
| I <sub>PLS</sub>    | Maximum pulsed switch current, pulse < 300 μs, 2% duty cycle          |      | 6   | A                   |
| T <sub>J</sub>      | Maximum junction temperature                                          |      | 125 | °C                  |
| T <sub>stg</sub>    | Storage temperature                                                   | −65  | 150 | °C                  |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.

### 7.2 ESD Ratings

|                    |                         | VALUE                                                                          | UNIT  |
|--------------------|-------------------------|--------------------------------------------------------------------------------|-------|
| V <sub>(ESD)</sub> | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±2000 |
|                    |                         | Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±1000 |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

### 7.3 Recommended Operating Conditions

|                        |                                               |                                    | MIN              | MAX               | UNIT |
|------------------------|-----------------------------------------------|------------------------------------|------------------|-------------------|------|
| V <sub>IN1,2</sub>     | Input voltage                                 |                                    | 0.8              | V <sub>BIAS</sub> | V    |
| V <sub>BIAS</sub>      | Bias voltage                                  |                                    | 2.5              | 5.5               | V    |
| V <sub>ON1,2</sub>     | ON voltage                                    |                                    | 0                | 5.5               | V    |
| V <sub>OUT1,2</sub>    | Output voltage                                |                                    |                  | V <sub>IN</sub>   | V    |
| V <sub>IH, ON1,2</sub> | High-level input voltage, ON1,2               | V <sub>BIAS</sub> = 2.5 V to 5.5 V | 1.2              | 5.5               | V    |
| V <sub>IL, ON1,2</sub> | Low-level input voltage, ON1,2                | V <sub>BIAS</sub> = 2.5 V to 5.5 V | 0                | 0.5               | V    |
| C <sub>IN1,2</sub>     | Input capacitor                               |                                    | 1 <sup>(1)</sup> |                   | μF   |
| T <sub>A</sub>         | Operating free-air temperature <sup>(2)</sup> |                                    | −40              | 105               | °C   |

- (1) See the [Application Information](#) section.
- (2) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature [T<sub>A(max)</sub>] is dependent on the maximum operating junction temperature [T<sub>J(max)</sub>], the maximum power dissipation of the device in the application [P<sub>D(max)</sub>], and the junction-to-ambient thermal resistance of the part/package in the application (R<sub>θJA</sub>), as given by the following equation: T<sub>A(max)</sub> = T<sub>J(max)</sub> − (R<sub>θJA</sub> × P<sub>D(max)</sub>).

### 7.4 Thermal Information

| THERMAL METRIC <sup>(1) (2)</sup> |                                            | TPS22968   | UNIT |
|-----------------------------------|--------------------------------------------|------------|------|
|                                   |                                            | DPU (WSON) |      |
|                                   |                                            | 14 PINS    |      |
| R <sub>θJA</sub>                  | Junction-to-ambient thermal resistance     | 62.5       | °C/W |
| R <sub>θJC(top)</sub>             | Junction-to-case (top) thermal resistance  | 70.2       | °C/W |
| R <sub>θJB</sub>                  | Junction-to-board thermal resistance       | 23.2       | °C/W |
| ψ <sub>JT</sub>                   | Junction-to-top characterization parameter | 2.5        | °C/W |

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.
- (2) For thermal estimates of this device based on PCB copper area, see the [TI PCB Thermal Calculator](#).

## Thermal Information (continued)

| THERMAL METRIC <sup>(1)</sup> <sup>(2)</sup> |                                              | TPS22968   | UNIT |
|----------------------------------------------|----------------------------------------------|------------|------|
|                                              |                                              | DPU (WSON) |      |
|                                              |                                              | 14 PINS    |      |
| $\psi_{JB}$                                  | Junction-to-board characterization parameter | 23.2       | °C/W |
| $R_{\theta JC(bot)}$                         | Junction-to-case (bottom) thermal resistance | 9          | °C/W |

## 7.5 Electrical Characteristics ( $V_{BIAS} = 5\text{ V}$ )

Unless otherwise noted, the specification in the following table applies over the operating ambient temperature  $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$  (full) and  $V_{BIAS} = 5\text{ V}$ . Typical values are for  $T_A = 25^{\circ}\text{C}$  (unless otherwise noted).

| PARAMETER                            |                                                      | TEST CONDITIONS                                                                                                                    |                            | T <sub>A</sub>  | MIN  | TYP | MAX | UNIT |
|--------------------------------------|------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------|----------------------------|-----------------|------|-----|-----|------|
| POWER SUPPLIES AND CURRENTS          |                                                      |                                                                                                                                    |                            |                 |      |     |     |      |
| I <sub>Q</sub> , V <sub>BIAS</sub>   | V <sub>BIAS</sub> quiescent current (both channels)  | I <sub>OUT1</sub> = I <sub>OUT2</sub> = 0, V <sub>IN1,2</sub> = V <sub>ON1,2</sub> = V <sub>BIAS</sub> = 5 V                       |                            | −40°C to +105°C | 55   | 70  |     | μA   |
|                                      | V <sub>BIAS</sub> quiescent current (single channel) | I <sub>OUT1</sub> = I <sub>OUT2</sub> = 0, V <sub>ON2</sub> = 0 V, V <sub>IN1,2</sub> = V <sub>ON1</sub> = V <sub>BIAS</sub> = 5 V |                            | −40°C to +105°C | 55   | 68  |     | μA   |
| I <sub>SD</sub> , V <sub>BIAS</sub>  | V <sub>BIAS</sub> shutdown current                   | V <sub>ON1,2</sub> = 0 V, V <sub>OUT1,2</sub> = 0 V                                                                                |                            | −40°C to +105°C | 1    | 2   |     | μA   |
| I <sub>SD</sub> , V <sub>IN1,2</sub> | V <sub>IN1,2</sub> shutdown current (per channel)    | V <sub>ON1,2</sub> = 0 V, V <sub>OUT1,2</sub> = 0 V                                                                                | V <sub>IN1,2</sub> = 5 V   | −40°C to +85°C  | 0.5  | 8   |     | μA   |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 10  |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN1,2</sub> = 3.3 V | −40°C to +85°C  | 0.1  | 3   |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 4   |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN1,2</sub> = 1.8 V | −40°C to +85°C  | 0.07 | 2   |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 3   |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN1,2</sub> = 1.2 V | −40°C to +85°C  | 0.05 | 1   |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 2   |     |      |
|                                      | V <sub>IN1,2</sub> = 0.8 V                           | −40°C to +85°C                                                                                                                     | 0.04                       | 1               |      |     |     |      |
|                                      |                                                      | −40°C to +105°C                                                                                                                    |                            | 2               |      |     |     |      |
| I <sub>ON1,2</sub>                   | ON pin input leakage current                         | V <sub>ON</sub> = 5.5 V                                                                                                            |                            | −40°C to +105°C |      | 0.1 |     | μA   |
| RESISTANCE CHARACTERISTICS           |                                                      |                                                                                                                                    |                            |                 |      |     |     |      |
| R <sub>ON</sub>                      | On-state resistance                                  | I <sub>OUT</sub> = −200 mA, V <sub>BIAS</sub> = 5 V<br>V <sub>ON1,2</sub> = 5 V                                                    | V <sub>IN</sub> = 5 V      | 25°C            | 27   | 36  |     | mΩ   |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +85°C  |      | 40  |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 42  |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN</sub> = 3.3 V    | 25°C            | 25   | 34  |     | mΩ   |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +85°C  |      | 38  |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 40  |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN</sub> = 1.8 V    | 25°C            | 25   | 34  |     | mΩ   |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +85°C  |      | 38  |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 40  |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN</sub> = 1.5 V    | 25°C            | 25   | 34  |     | mΩ   |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +85°C  |      | 38  |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 40  |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN</sub> = 1.2 V    | 25°C            | 25   | 34  |     | mΩ   |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +85°C  |      | 38  |     |      |
|                                      |                                                      |                                                                                                                                    |                            | −40°C to +105°C |      | 40  |     |      |
|                                      |                                                      |                                                                                                                                    | V <sub>IN</sub> = 0.8 V    | 25°C            | 25   | 34  |     | mΩ   |
| −40°C to +85°C                       |                                                      | 38                                                                                                                                 |                            |                 |      |     |     |      |
| −40°C to +105°C                      |                                                      | 40                                                                                                                                 |                            |                 |      |     |     |      |
| R <sub>PD</sub> <sup>(1)</sup>       | Output pulldown resistance                           | V <sub>IN</sub> = 5 V, V <sub>ON</sub> = 0 V, I <sub>OUT</sub> = 10 mA                                                             |                            | −40°C to +105°C | 270  | 320 |     | Ω    |

(1) TPS22968 only.

## 7.6 Electrical Characteristics ( $V_{BIAS} = 2.5\text{ V}$ )

Unless otherwise noted, the specification in the following table applies over the operating ambient temperature  $-40\text{ }^{\circ}\text{C} \leq T_A \leq +105\text{ }^{\circ}\text{C}$  (full) and  $V_{BIAS} = 2.5\text{ V}$ . Typical values are for  $T_A = 25\text{ }^{\circ}\text{C}$  (unless otherwise noted).

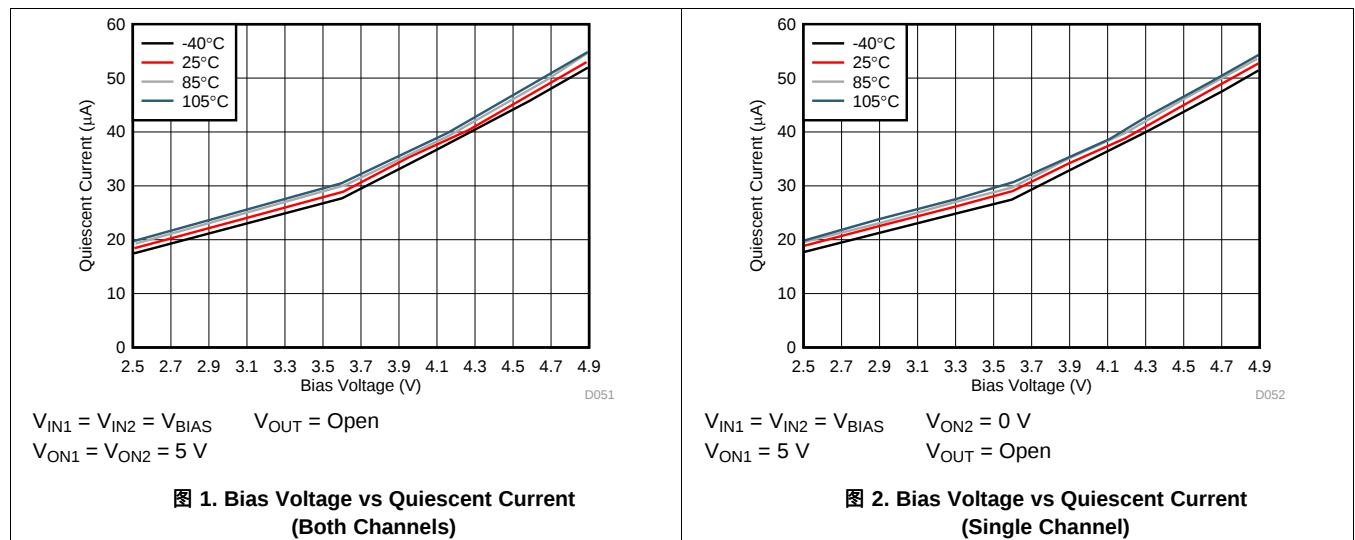
| PARAMETER                            |                                                      | TEST CONDITIONS                                                                                                                      |                            | T <sub>A</sub>  | MIN  | TYP | MA<br>X | UNIT |
|--------------------------------------|------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------|----------------------------|-----------------|------|-----|---------|------|
| POWER SUPPLIES AND CURRENTS          |                                                      |                                                                                                                                      |                            |                 |      |     |         |      |
| I <sub>Q</sub> , V <sub>BIAS</sub>   | V <sub>BIAS</sub> quiescent current (both channels)  | I <sub>OUT1</sub> = I <sub>OUT2</sub> = 0, V <sub>IN1,2</sub> = V <sub>ON1,2</sub> = V <sub>BIAS</sub> = 2.5 V                       |                            | −40°C to +105°C | 18   | 27  |         | μA   |
|                                      | V <sub>BIAS</sub> quiescent current (single channel) | I <sub>OUT1</sub> = I <sub>OUT2</sub> = 0, V <sub>ON2</sub> = 0 V, V <sub>IN1,2</sub> = V <sub>ON1</sub> = V <sub>BIAS</sub> = 2.5 V |                            | −40°C to +105°C | 18   | 27  |         | μA   |
| I <sub>SD</sub> , V <sub>BIAS</sub>  | V <sub>BIAS</sub> shutdown current                   | V <sub>ON1,2</sub> = 0 V, V <sub>OUT1,2</sub> = 0 V                                                                                  |                            | −40°C to +105°C | 0.5  | 2   |         | μA   |
| I <sub>SD</sub> , V <sub>IN1,2</sub> | V <sub>IN1,2</sub> shutdown current (per channel)    | V <sub>ON1,2</sub> = 0 V, V <sub>OUT1,2</sub> = 0 V                                                                                  | V <sub>IN1,2</sub> = 2.5 V | −40°C to +85°C  | 0.1  | 2   | μA      |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 4   |         |      |
|                                      |                                                      |                                                                                                                                      | V <sub>IN1,2</sub> = 1.8 V | −40°C to +85°C  | 0.07 | 2   |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 3   |         |      |
|                                      |                                                      |                                                                                                                                      | V <sub>IN1,2</sub> = 1.2 V | −40°C to +85°C  | 0.05 | 1   |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 2   |         |      |
|                                      |                                                      |                                                                                                                                      | V <sub>IN1,2</sub> = 0.8 V | −40°C to +85°C  | 0.04 | 1   |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 2   |         |      |
| I <sub>ON1,2</sub>                   | ON pin input leakage current                         | V <sub>ON</sub> = 5.5 V                                                                                                              |                            | −40°C to +85°C  |      | 0.1 |         | μA   |
| RESISTANCE CHARACTERISTICS           |                                                      |                                                                                                                                      |                            |                 |      |     |         |      |
| R <sub>ON</sub>                      | On-state resistance                                  | I <sub>OUT</sub> = −200 mA, V <sub>BIAS</sub> = 2.5 V<br>V <sub>ON1,2</sub> = 5 V                                                    | V <sub>IN</sub> = 2.5 V    | 25°C            | 30   | 39  | mΩ      |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +85°C  |      | 44  |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 46  |         |      |
|                                      |                                                      |                                                                                                                                      | V <sub>IN</sub> = 1.8 V    | 25°C            | 28   | 36  | mΩ      |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +85°C  |      | 41  |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 43  |         |      |
|                                      |                                                      |                                                                                                                                      | V <sub>IN</sub> = 1.5 V    | 25°C            | 28   | 36  | mΩ      |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +85°C  |      | 41  |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 43  |         |      |
|                                      |                                                      |                                                                                                                                      | V <sub>IN</sub> = 1.2 V    | 25°C            | 27   | 36  | mΩ      |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +85°C  |      | 41  |         |      |
|                                      |                                                      |                                                                                                                                      |                            | −40°C to +105°C |      | 43  |         |      |
| V <sub>IN</sub> = 0.8 V              | 25°C                                                 | 26                                                                                                                                   | 35                         | mΩ              |      |     |         |      |
|                                      | −40°C to +85°C                                       |                                                                                                                                      | 39                         |                 |      |     |         |      |
|                                      | −40°C to +105°C                                      |                                                                                                                                      | 41                         |                 |      |     |         |      |
| R <sub>PD</sub> <sup>(1)</sup>       | Output pulldown resistance                           | V <sub>IN</sub> = 2.5 V, V <sub>ON</sub> = 0 V, I <sub>OUT</sub> = 10 mA                                                             |                            | −40°C to +105°C | 270  | 320 |         | Ω    |

(1) TPS22968 only.

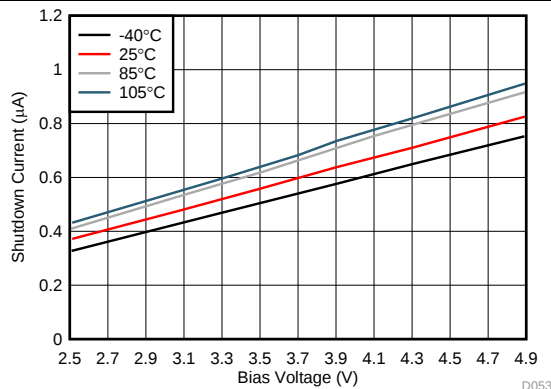
## 7.7 Switching Characteristics

| PARAMETER                                                                                                                     |                            | TEST CONDITION                                               | MIN | TYP  | MAX | UNIT |
|-------------------------------------------------------------------------------------------------------------------------------|----------------------------|--------------------------------------------------------------|-----|------|-----|------|
| <b>V<sub>IN</sub> = V<sub>ON</sub> = V<sub>BIAS</sub> = 5 V, T<sub>A</sub> = 25 °C (unless otherwise noted)</b>               |                            |                                                              |     |      |     |      |
| t <sub>ON</sub>                                                                                                               | Turnon time                | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 1128 |     | μs   |
| t <sub>OFF</sub>                                                                                                              | Turnoff time               | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 5    |     |      |
| t <sub>R</sub>                                                                                                                | V <sub>OUT</sub> rise time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 1387 |     |      |
| t <sub>F</sub>                                                                                                                | V <sub>OUT</sub> fall time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 2    |     |      |
| t <sub>D</sub>                                                                                                                | ON delay time              | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 455  |     |      |
| <b>V<sub>IN</sub> = 0.8 V, V<sub>ON</sub> = V<sub>BIAS</sub> = 5 V, T<sub>A</sub> = 25 °C (unless otherwise noted)</b>        |                            |                                                              |     |      |     |      |
| t <sub>ON</sub>                                                                                                               | Turnon time                | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 508  |     | μs   |
| t <sub>OFF</sub>                                                                                                              | Turnoff time               | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 33   |     |      |
| t <sub>R</sub>                                                                                                                | V <sub>OUT</sub> rise time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 273  |     |      |
| t <sub>F</sub>                                                                                                                | V <sub>OUT</sub> fall time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 2    |     |      |
| t <sub>D</sub>                                                                                                                | ON delay time              | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 377  |     |      |
| <b>V<sub>IN</sub> = 2.5 V, V<sub>ON</sub> = 5 V, V<sub>BIAS</sub> = 2.5V, T<sub>A</sub> = 25 °C (unless otherwise noted)</b>  |                            |                                                              |     |      |     |      |
| t <sub>ON</sub>                                                                                                               | Turnon time                | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 1718 |     | μs   |
| t <sub>OFF</sub>                                                                                                              | Turnoff time               | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 7    |     |      |
| t <sub>R</sub>                                                                                                                | V <sub>OUT</sub> rise time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 1701 |     |      |
| t <sub>F</sub>                                                                                                                | V <sub>OUT</sub> fall time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 2    |     |      |
| t <sub>D</sub>                                                                                                                | ON delay time              | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 859  |     |      |
| <b>V<sub>IN</sub> = 0.8 V, V<sub>ON</sub> = 5 V, V<sub>BIAS</sub> = 2.5 V, T<sub>A</sub> = 25 °C (unless otherwise noted)</b> |                            |                                                              |     |      |     |      |
| t <sub>ON</sub>                                                                                                               | Turnon time                | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 1117 |     | μs   |
| t <sub>OFF</sub>                                                                                                              | Turnoff time               | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 30   |     |      |
| t <sub>R</sub>                                                                                                                | V <sub>OUT</sub> rise time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 651  |     |      |
| t <sub>F</sub>                                                                                                                | V <sub>OUT</sub> fall time | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 2    |     |      |
| t <sub>D</sub>                                                                                                                | ON delay time              | R <sub>L</sub> = 10 Ω, C <sub>L</sub> = 0.1 μF, CT = 1000 pF |     | 775  |     |      |

## 7.8 Typical DC Characteristics

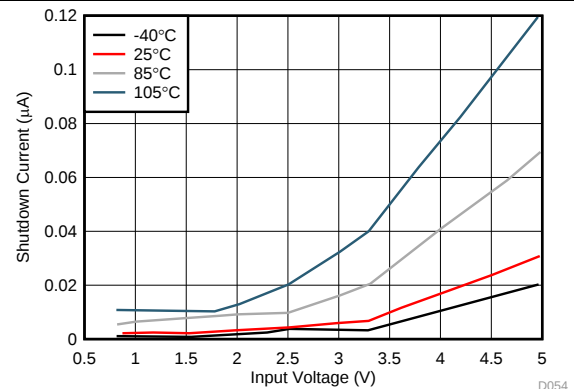


## Typical DC Characteristics (接下页)



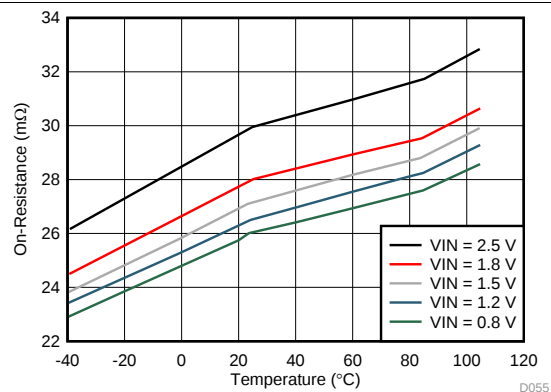
$V_{IN1} = V_{IN2} = V_{BIAS}$   $V_{OUT} = 0\text{ V}$   
 $V_{ON1} = V_{ON2} = 0\text{ V}$

图 3. Bias Voltage vs Shutdown Current (Both Channels)



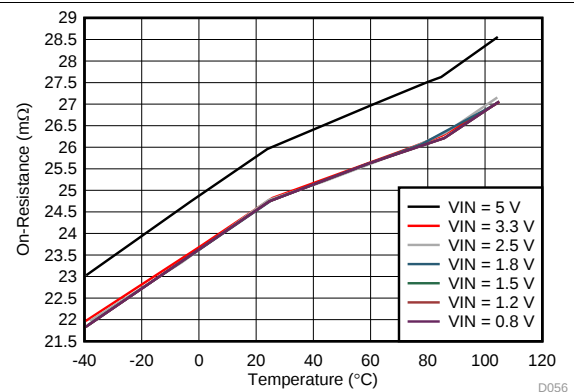
$V_{BIAS} = 5\text{ V}$   $V_{OUT} = 0\text{ V}$   
 $V_{ON1} = V_{ON2} = 0\text{ V}$

图 4. Input Voltage vs Shutdown Current



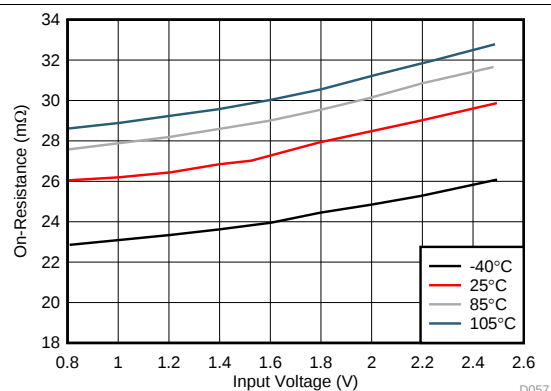
$V_{BIAS} = 2.5\text{ V}$   
 $I_{OUT} = -200\text{ mA}$

图 5. Temperature vs On-Resistance



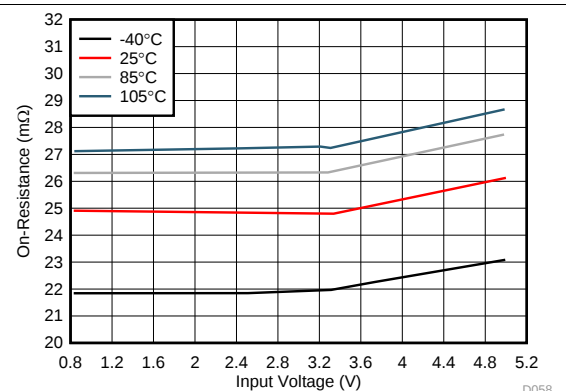
$V_{BIAS} = 5\text{ V}$   
 $I_{OUT} = -200\text{ mA}$

图 6. Temperature vs On-Resistance



$V_{BIAS} = 2.5\text{ V}$   
 $I_{OUT} = -200\text{ mA}$

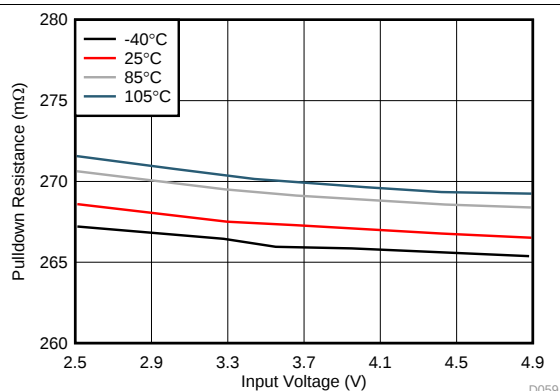
图 7. Input Voltage vs On-Resistance



$V_{BIAS} = 5\text{ V}$   
 $I_{OUT} = -200\text{ mA}$

图 8. Input Voltage vs On-Resistance

## Typical DC Characteristics (接下页)

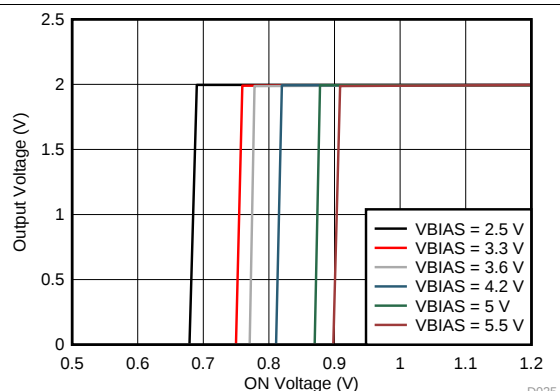


$V_{BIAS} = 5\text{ V}$

$I_{OUT} = 1\text{ mA}$

$V_{ON} = 0\text{ V}$

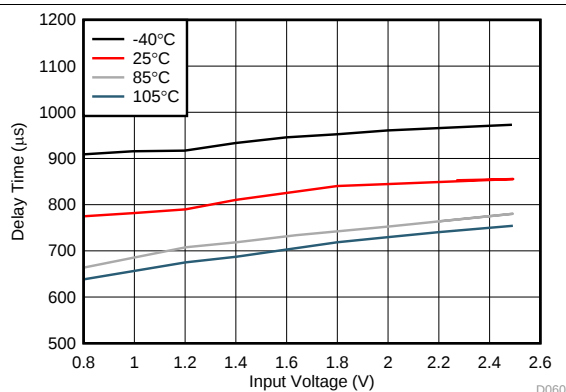
图 9. Input Voltage vs Pulldown Resistance (TPS22968 Only)  
(Single Channel)



$T_A = 25^\circ\text{C}$

$V_{IN} = 2\text{ V}$

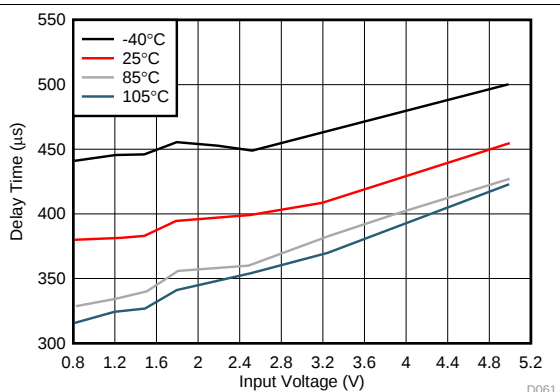
图 10. ON Voltage vs Output Voltage



$V_{BIAS} = 2.5\text{ V}$

$CT = 1\text{ nF}$

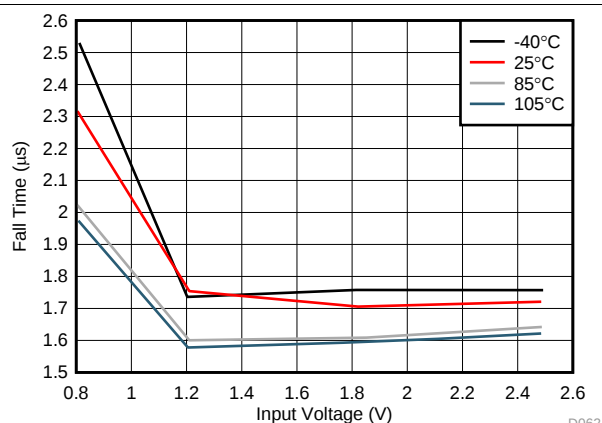
图 11. Input Voltage vs Delay Time



$V_{BIAS} = 5\text{ V}$

$CT = 1\text{ nF}$

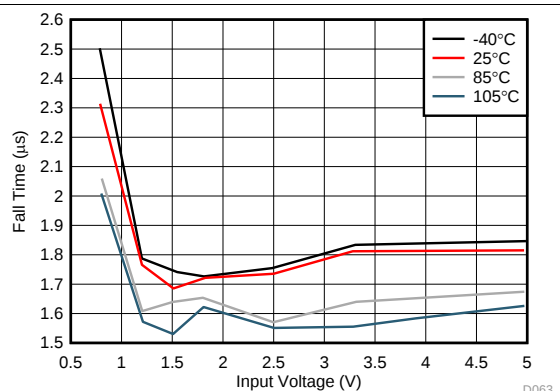
图 12. Input Voltage vs Delay Time



$V_{BIAS} = 2.5\text{ V}$

$CT = 1\text{ nF}$

图 13. Input Voltage vs Fall Time

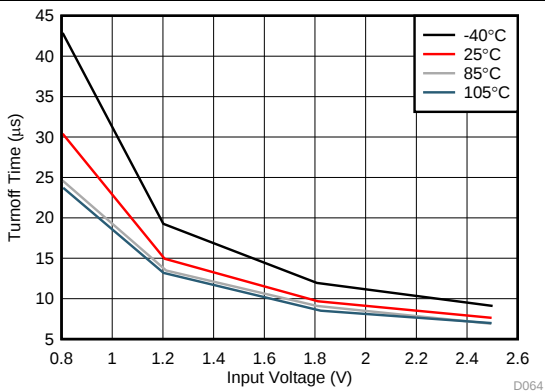


$V_{BIAS} = 5\text{ V}$

$CT = 1\text{ nF}$

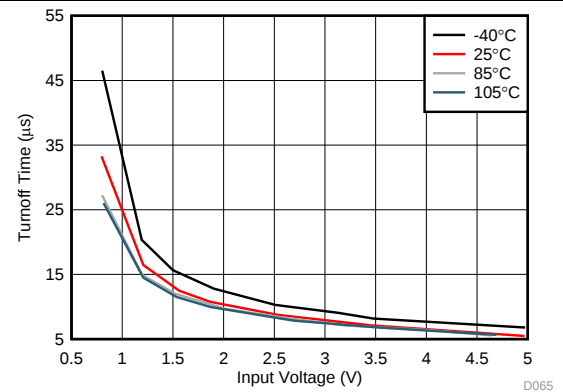
图 14. Input Voltage vs Fall Time

## Typical DC Characteristics (接下页)



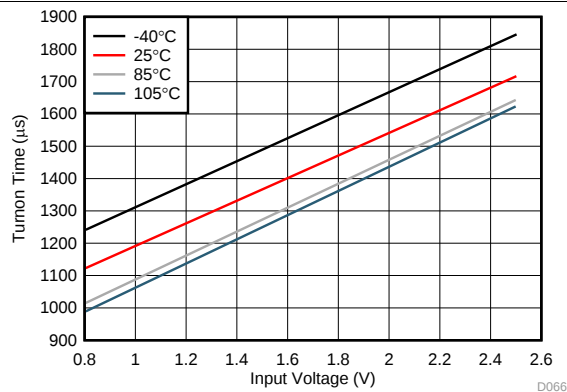
$V_{BIAS} = 2.5 \text{ V}$   
 $CT = 1 \text{ nF}$

图 15. Input Voltage vs Turnoff Time



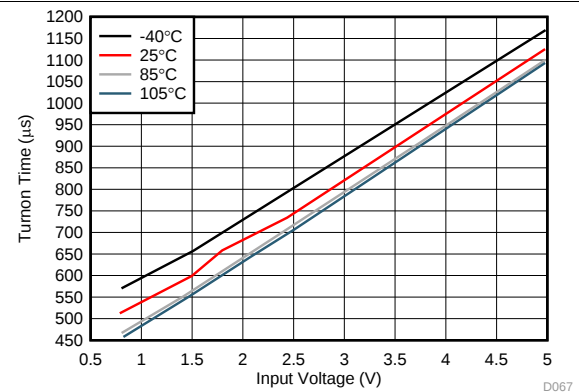
$V_{BIAS} = 5 \text{ V}$   
 $CT = 1 \text{ nF}$

图 16. Input Voltage vs Turnoff Time



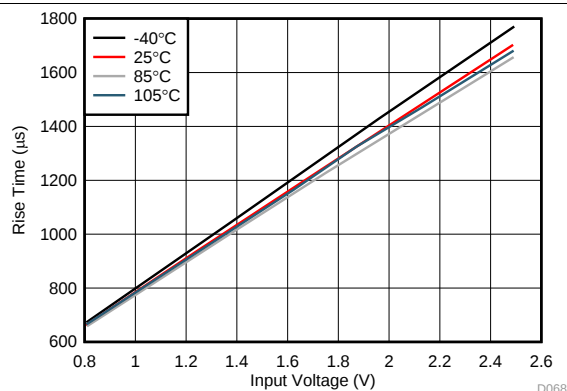
$V_{BIAS} = 2.5 \text{ V}$   
 $CT = 1 \text{ nF}$

图 17. Input Voltage vs Turnon Time



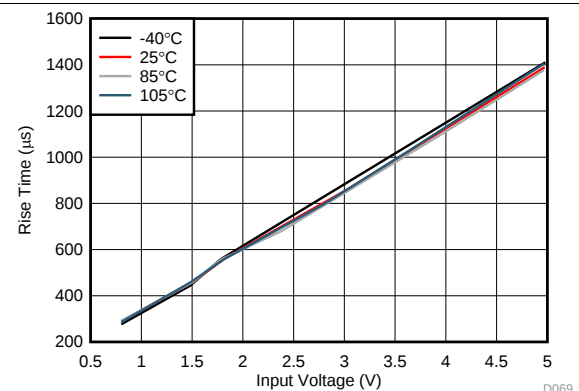
$V_{BIAS} = 5 \text{ V}$   
 $CT = 1 \text{ nF}$

图 18. Input Voltage vs Turnon Time



$V_{BIAS} = 2.5 \text{ V}$   
 $CT = 1 \text{ nF}$

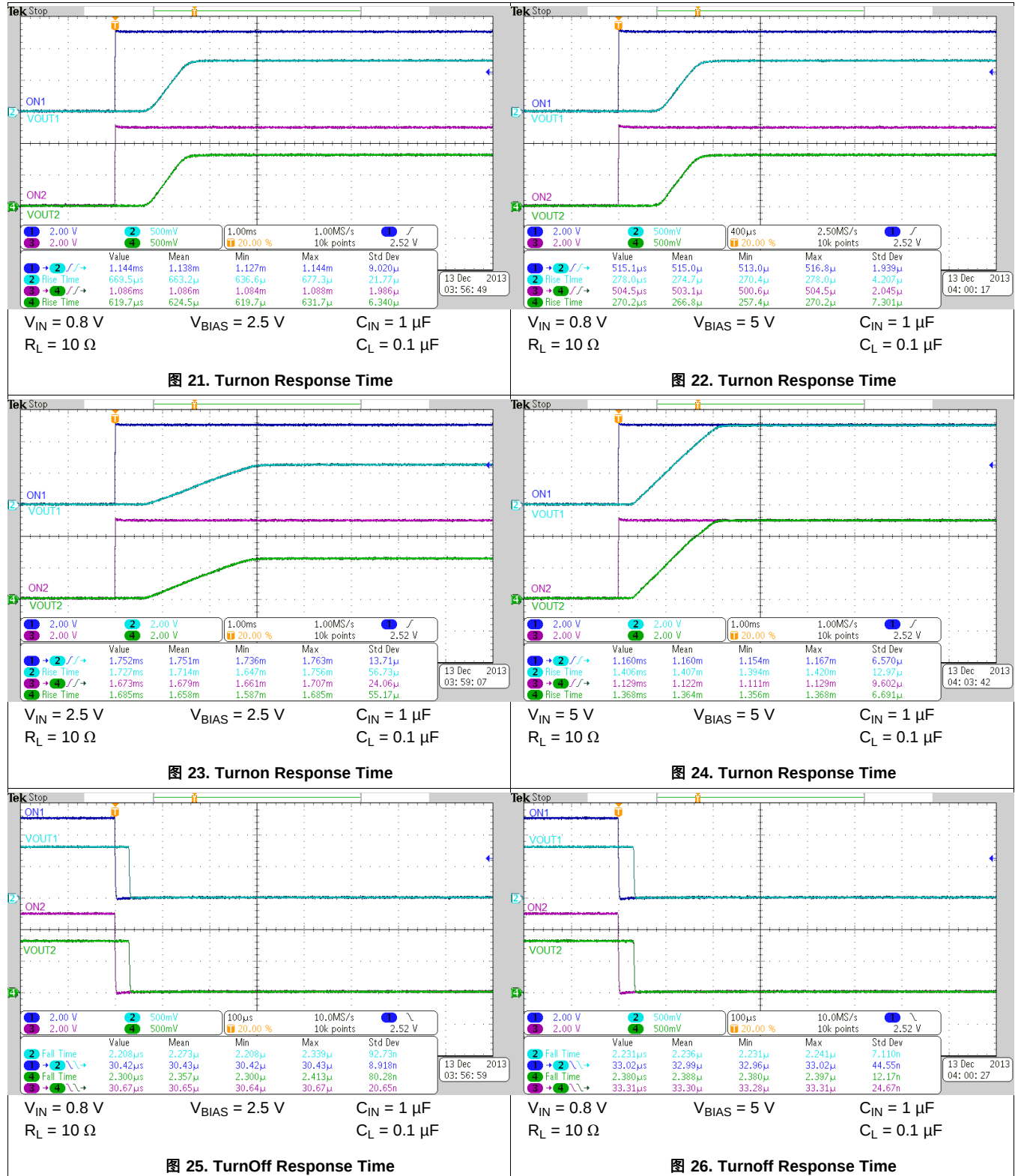
图 19. Input Voltage vs Rise Time



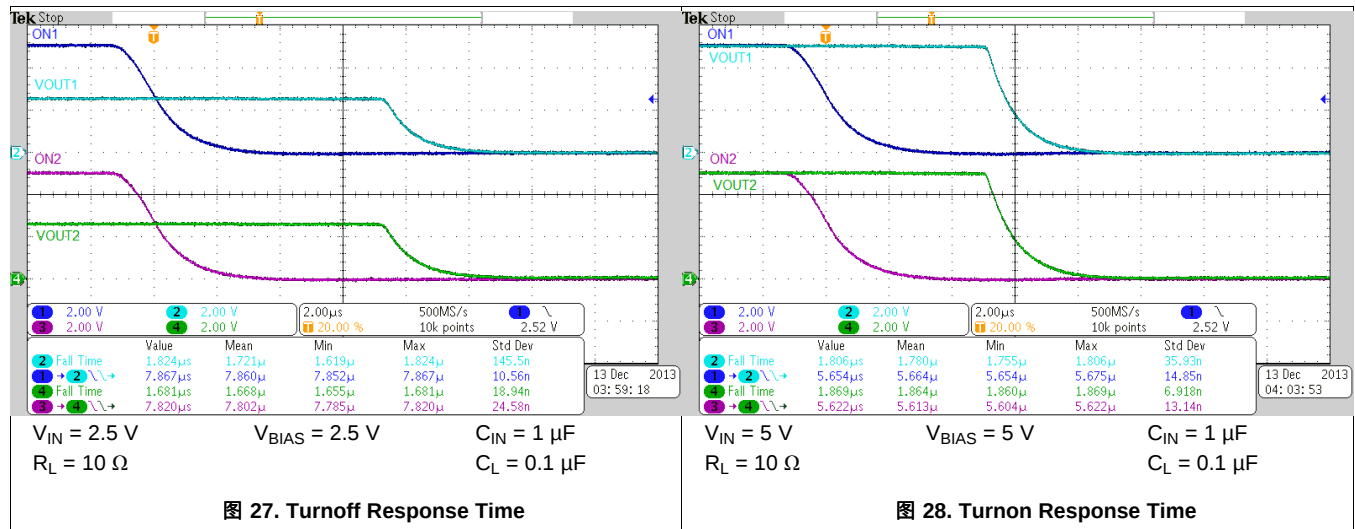
$V_{BIAS} = 5 \text{ V}$   
 $CT = 1 \text{ nF}$

图 20. Input Voltage vs Rise Time

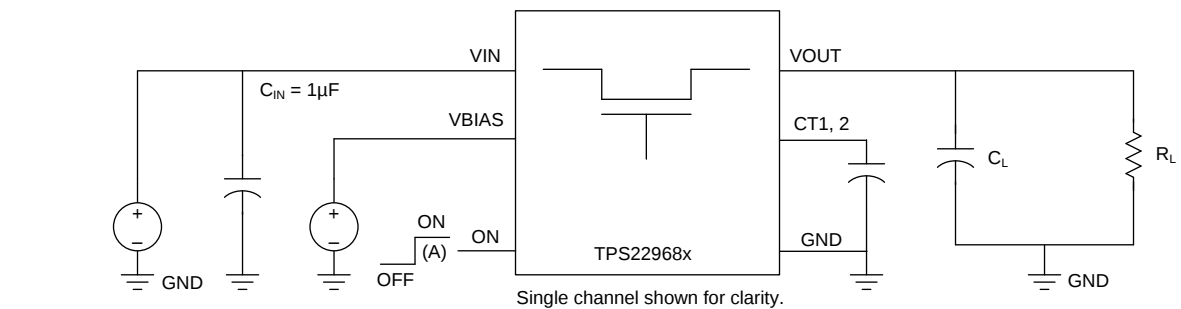
## 7.9 Typical AC Characteristics



## Typical AC Characteristics (接下页)

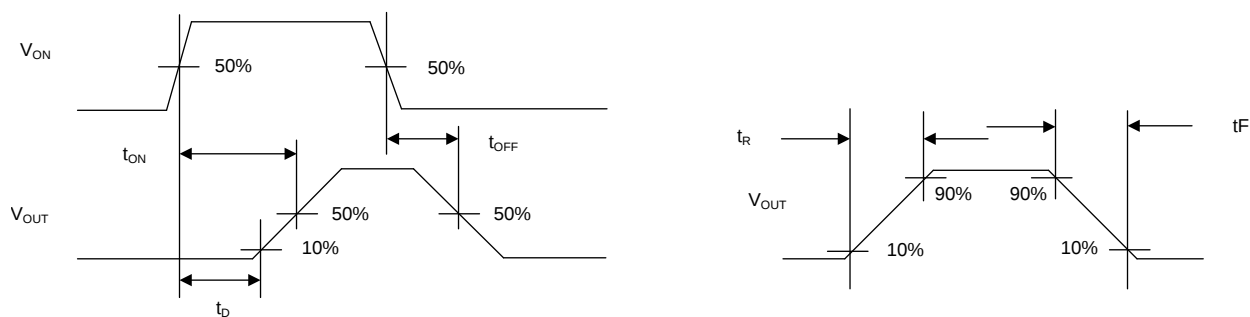


## 8 Parameter Measurement Information



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TEST CIRCUIT



TIMING DIAGRAMS

- A. Rise and fall times of the control signal is 100 ns.

**图 29. Test Circuit and Timing Waveforms**

## 9 Detailed Description

### 9.1 Overview

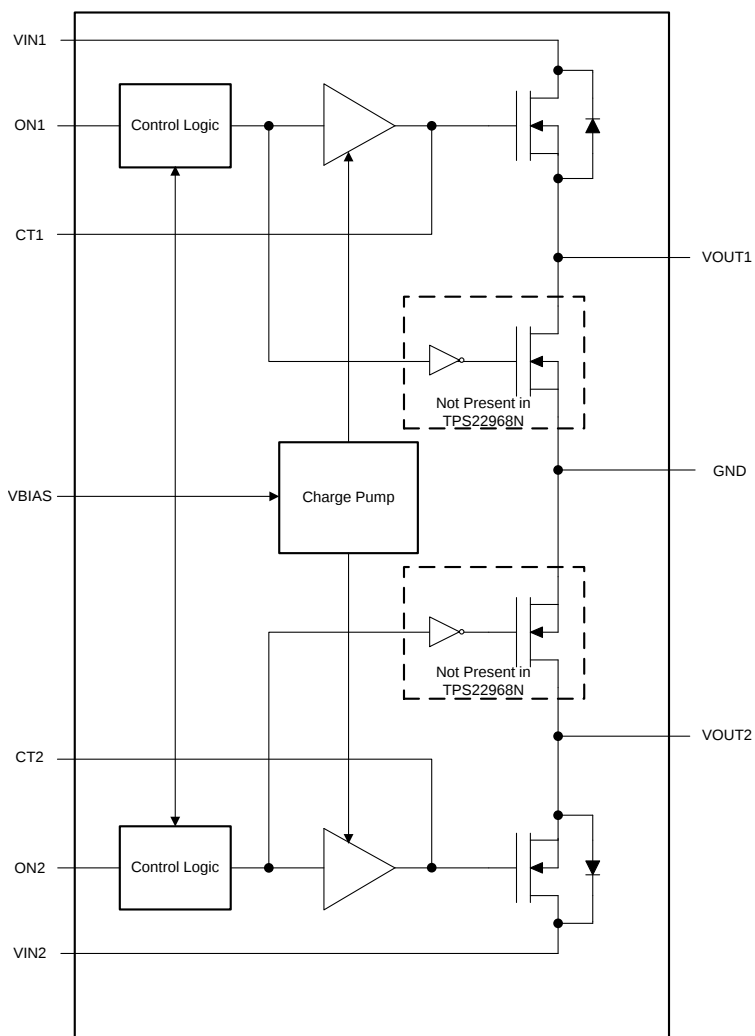
The TPS22968 is a 5.5-V, 4-A, dual-channel ultra-low  $R_{ON}$  load switch with controlled turnon. The device contains two N-channel MOSFETs. Each channel can support a maximum continuous current of 4 A and is controlled by an on and off GPIO-compatible input. The ON pin must be connected and cannot be left floating. The device is designed to control the turnon rate and therefore the inrush current. By controlling the inrush current, power supply sag can be reduced during turnon. The slew rate for each channel is set by connecting a capacitor to GND on the CT pins.

The slew rate is proportional to the capacitor on the CT pin. See the [Adjustable Rise Time](#) section to determine the correct CT value for a desired rise time.

The internal circuitry is powered by the VBIAS pin, which supports voltages from 2.5 V to 5.5 V. This circuitry includes the charge pump, QOD (optional), and control logic. For these internal blocks to function correctly, a voltage between 2.5 V and 5.5 V must be supplied to VBIAS.

When a voltage is supplied to VBIAS, the ON1 pin goes low, and the ON2 pins go low, the QOD turns on. This connects VOUT1 and VOUT2 to GND through an on-chip resistor. The typical pulldown resistance ( $R_{PD}$ ) is 270  $\Omega$ .

### 9.2 Functional Block Diagram



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## 9.3 Feature Description

### 9.3.1 ON and OFF Control

The ON pins control the state of the switch. Asserting ON high enables the switch. ON is active high and has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic threshold. It can be used with any microcontroller with 1.2 V or higher GPIO voltage. This pin cannot be left floating and must be tied either high or low for proper functionality.

### 9.3.2 Input Capacitor (Optional)

When the switch turns on into a discharged load capacitor or short-circuit, a capacitor must be placed between VIN and GND to limit the voltage drop on the input supply caused by transient inrush currents. A 1-μF ceramic capacitor ( $C_{IN}$ ), placed close to the pins, is sufficient. Higher values of  $C_{IN}$  can be used to further reduce the voltage drop during high-current application. When switching heavy loads, TI recommends having an input capacitor 10x higher than the output capacitor to avoid excessive voltage drop.

### 9.3.3 Output Capacitor (Optional)

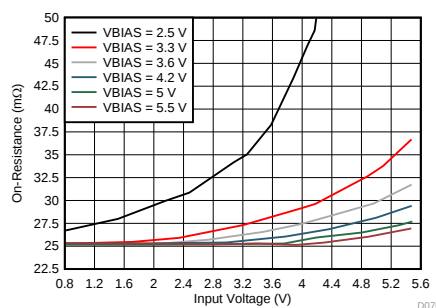
TI highly recommends a  $C_{IN}$  greater than  $C_L$ , because of the integrated body diode in the NMOS switch. A  $C_L$  greater than  $C_{IN}$  can cause the voltage on VOUT to exceed VIN when the system supply is removed. This could result in current flow through the body diode from VOUT to VIN. TI recommends a  $C_{IN}$  to  $C_L$  ratio of 10 to 1 for minimizing  $V_{IN}$  dip caused by inrush currents during startup.

### 9.3.4 QOD (Optional)

The TPS22968 includes a QOD feature. When the switch is disabled, a discharge resistor is connected between VOUT and GND. This resistor has a typical value of 270 Ω and prevents the output from floating while the switch is disabled.

### 9.3.5 VIN and VBIAS Voltage Range

For optimal  $R_{ON}$  performance, make sure  $V_{IN} \leq V_{BIAS}$ . The device is still functional if  $V_{IN} > V_{BIAS}$ , but it exhibits  $R_{ON}$  greater than what is listed in the [Electrical Characteristics \( \$V\_{BIAS} = 5\text{ V}\$ \)](#) and [Electrical Characteristics \( \$V\_{BIAS} = 2.5\text{ V}\$ \)](#) table. See [Figure 30](#) for an example of a typical device. Notice the increasing  $R_{ON}$  as  $V_{IN}$  exceeds  $V_{BIAS}$  voltage. Be sure to never exceed the maximum voltage rating for  $V_{IN}$  and  $V_{BIAS}$ .



Temperature = 25°C

$I_{OUT} = 200\text{ mA}$

**图 30. On-Resistance vs Input Voltage**

## Feature Description (接下页)

### 9.3.6 Adjustable Rise Time

A capacitor to GND on the CT pins sets the slew rate for each channel. The capacitor to GND on the CT pins must be rated for 25 V and above. An approximate formula for the relationship between CT and slew rate with  $V_{BIAS} = 5\text{ V}$  is shown in 公式 1.

$$SR = 0.32 \times CT + 13.7$$

where

- SR is the slew rate (in  $\mu\text{s/V}$ )
- CT is the capacitance value on the CT pin (in pF)
- The units for the constant 13.7 is in  $\mu\text{s/V}$ .

(1)

Rise time can be calculated by multiplying the input voltage by the slew rate. 表 1 contains rise time values measured on a typical device.

**表 1. Rise Time Table**

| CTx (pF) | Typical values at 25°C with a 25-V X7R 10% ceramic capacitor on CT <sup>(1)</sup> |             |             |             |             |            |             |
|----------|-----------------------------------------------------------------------------------|-------------|-------------|-------------|-------------|------------|-------------|
|          | VIN = 5 V                                                                         | VIN = 3.3 V | VIN = 2.5 V | VIN = 1.8 V | VIN = 1.5 V | VIN = 1.2V | VIN = 0.8 V |
| 0        | 65                                                                                | 48          | 41          | 35          | 31          | 29         | 24          |
| 220      | 378                                                                               | 253         | 197         | 152         | 131         | 111        | 83          |
| 470      | 704                                                                               | 474         | 363         | 272         | 234         | 192        | 140         |
| 1000     | 1387                                                                              | 931         | 717         | 544         | 449         | 372        | 273         |
| 2200     | 3062                                                                              | 2021        | 1536        | 1173        | 991         | 825        | 595         |
| 4700     | 7091                                                                              | 4643        | 3547        | 2643        | 2213        | 1828       | 1349        |
| 10000    | 14781                                                                             | 9856        | 7330        | 5507        | 4600        | 3841       | 2805        |

(1) RISE TIME ( $\mu\text{s}$ ) 10% - 90%,  $C_L = 0.1\text{ }\mu\text{F}$ ,  $C_{IN} = 1\text{ }\mu\text{F}$ ,  $R_L = 10\text{ }\Omega$ ,  $V_{BIAS} = 5\text{ V}$

## 9.4 Device Functional Modes

表 2 lists the device function table.

**表 2. Functional Table**

| ONx | VINx to VOUTx | VOUTx to GND |
|-----|---------------|--------------|
| L   | Off           | On           |
| H   | On            | Off          |

## 10 Application and Implementation

### 注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 10.1 Application Information

This section highlights some of the design considerations for implementing this device in various applications. A PSPICE model for this device is also available on the [product page](#) for additional information.

#### 10.1.1 Parallel Configuration

To increase the current capabilities and lower the  $R_{ON}$  by approximately 50%, both channels can be placed in parallel as shown in [图 31](#) (parallel configuration). With this configuration, the CT1 and CT2 pins can be tied together to use one capacitor, CT, as shown in [图 31](#). With a single CT capacitor, the rise time is half of the typical rise-time value. Refer to the [表 1](#) for typical timing values.

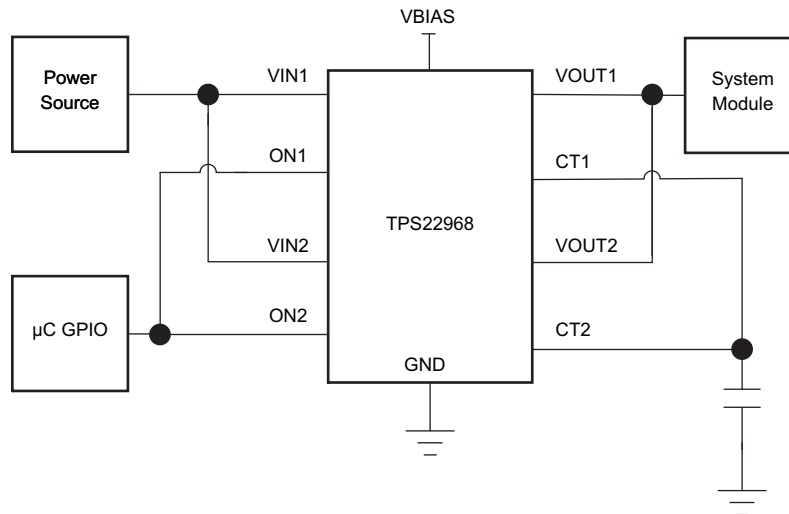


图 31. Parallel Configuration

## Application Information (接下页)

### 10.1.2 Standby Power Reduction

Any end equipment that is powered from the battery has a need to reduce current consumption to keep the battery charged for a longer time. TPS22968 helps to accomplish this by turning off the supply to the modules that are in standby state, and therefore, significantly reduces the leakage current overhead of the standby modules. See 图 32.

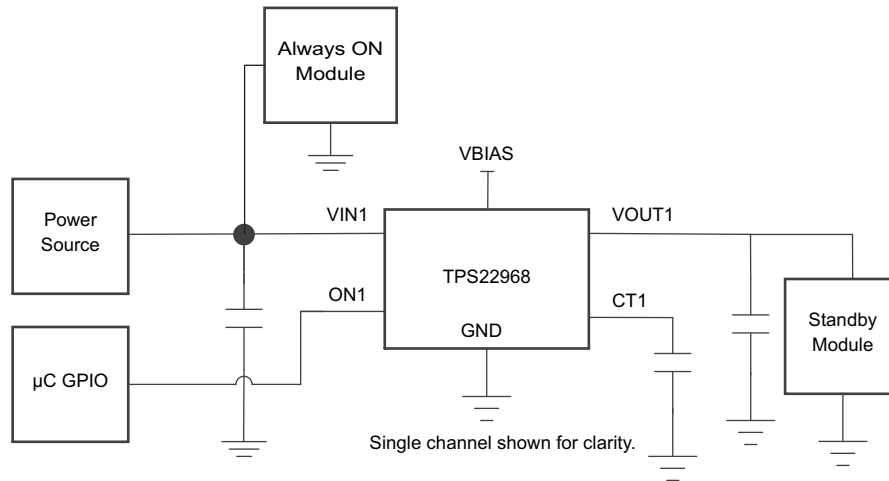


图 32. Standby Power Reduction

### 10.1.3 Power Supply Sequencing Without a GPIO Input

In many end equipments, there is a need to power up various modules in a predetermined manner. The TPS22968 can solve the problem of power sequencing without adding any complexity to the overall system. See 图 33.

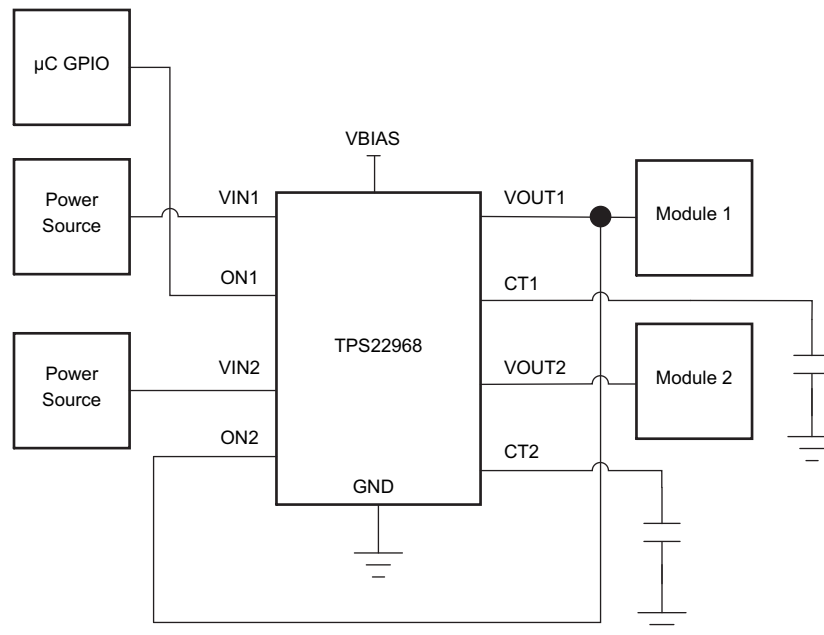
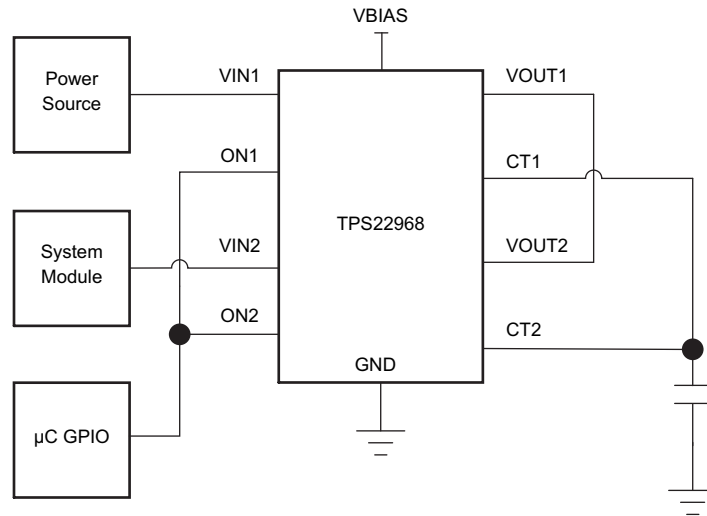


图 33. Power Sequencing Without a GPIO Input

## Application Information (接下页)

### 10.1.4 Reverse Current Blocking

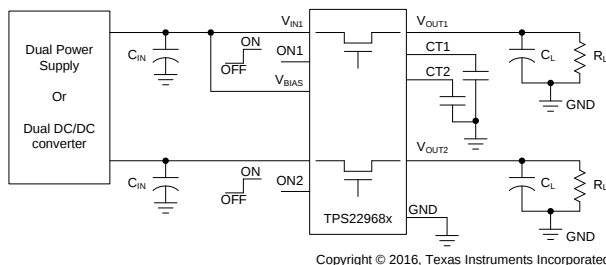
In certain applications, it may be desirable to have reverse current blocking. Reverse current blocking prevents current from flowing from the output to the input of the load switch when the device is disabled. With the following configuration, the TPS22968 can be converted into a single-channel switch with reverse current blocking. In this configuration, VIN1 or VIN2 can be used as the input and VIN2 or VIN1 is the output. See [图 34](#).



**图 34. Reverse Current Blocking**

## 10.2 Typical Application

This application demonstrates how the TPS22968 can be used to power downstream modules with large capacitances. The example in 图 35 TPS22968 is powering a 100-μF capacitive output load.



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图 35. Typical Application Schematic for Powering a Downstream Module

### 10.2.1 Design Requirements

For this design example, use the following 表 3 as the input parameters.

表 3. Design Parameters

| DESIGN PARAMETER                     | EXAMPLE VALUE |
|--------------------------------------|---------------|
| V <sub>IN</sub>                      | 3.3 V         |
| V <sub>BIAS</sub>                    | 5 V           |
| Load current                         | 4 A           |
| Output capacitance (C <sub>L</sub> ) | 22 μF         |
| Allowable inrush current on VOUT     | 0.33 A        |

### 10.2.2 Detailed Design Procedure

To begin the design process, the designer must know the following:

- V<sub>IN</sub> voltage
- V<sub>BIAS</sub> voltage
- Load current
- Allowable inrush current on VOUT due to C<sub>L</sub> capacitor

#### 10.2.2.1 VIN to VOUT Voltage Drop

The V<sub>IN</sub> to V<sub>OUT</sub> voltage drop in the device is determined by the R<sub>ON</sub> of the device and the load current. The R<sub>ON</sub> of the device depends upon the V<sub>IN</sub> and V<sub>BIAS</sub> conditions of the device. Refer to the R<sub>ON</sub> specification of the device in the [Electrical Characteristics \(V<sub>BIAS</sub> = 5 V\)](#) and [Electrical Characteristics \(V<sub>BIAS</sub> = 2.5 V\)](#). After the R<sub>ON</sub> of the device is determined based upon the V<sub>IN</sub> and V<sub>BIAS</sub> conditions, use 公式 2 to calculate the V<sub>IN</sub> to V<sub>OUT</sub> voltage drop:

$$\Delta V = I_{\text{LOAD}} \times R_{\text{ON}}$$

where

- ΔV is the voltage drop from V<sub>IN</sub> to V<sub>OUT</sub>
- I<sub>LOAD</sub> is the load current
- R<sub>ON</sub> is the On-resistance of the device for a specific V<sub>IN</sub> and V<sub>BIAS</sub> combination

An appropriate I<sub>LOAD</sub> must be chosen such that the I<sub>MAX</sub> specification of the device is not violated.

#### 10.2.2.2 Inrush Current

To determine how much inrush current is caused by the C<sub>L</sub> capacitor, use 公式 3.

$$I_{\text{INRUSH}} = C_L \times \frac{dV_{\text{OUT}}}{dt}$$

where

- $I_{INRUSH}$  is the amount of inrush caused by  $C_L$
- $C_L$  is the capacitance on  $V_{OUT}$
- $dt$  is the time it takes for change in  $V_{OUT}$  during the ramp up of  $V_{OUT}$  when the device is enabled
- $dV_{OUT}$  is the change in  $V_{OUT}$  during the ramp up of  $V_{OUT}$  when the device is enabled (3)

The device offers adjustable rise time for  $V_{OUT}$ . This feature allows the user to control the inrush current during turnon through the CTx pins. The appropriate rise time can be calculated using the design requirements and the inrush current equation ( 公式 3). See 公式 4 and 公式 5.

$$330 \text{ mA} = 22 \text{ } \mu\text{F} \times 3.3 \text{ V} / dt \quad (4)$$

$$dt = 220 \text{ } \mu\text{s} \quad (5)$$

To ensure an inrush current of less than 330 mA, choose a CT based on 表 1 or 公式 1 value that yields a rise time of more than 220  $\mu\text{s}$ . See the oscilloscope captures in the [Application Curves](#) for an example of how the CT capacitor can be used to reduce inrush current. See 表 1 for correlation between rise times and CT values.

An appropriate  $C_L$  value must be placed on  $V_{OUT}$  such that the  $I_{MAX}$  and  $I_{PLS}$  specifications of the device are not violated.

### 10.2.2.3 Thermal Considerations

The maximum IC junction temperature must be restricted to 125°C under normal operating conditions. To calculate the maximum allowable dissipation,  $P_{D(max)}$  for a given output current and ambient temperature, use 公式 6.

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{R_{\theta JA}}$$

where

- $P_{D(max)}$  is the maximum allowable power dissipation
- $T_{J(max)}$  is the maximum allowable junction temperature (125°C for the TPS22968)
- $T_A$  is the ambient temperature of the device
- $R_{\theta JA}$  is the junction to air thermal impedance. See the [Thermal Information](#) table. This parameter is highly dependent upon board layout. (6)

公式 7 到 公式 10 和 公式 11 到 公式 13 show two examples to determine how to use this information correctly:

For  $V_{BIAS} = 5 \text{ V}$ ,  $V_{IN} = 5 \text{ V}$ , the maximum ambient temperature with a 4-A load through each channel can be determined by using 公式 7 to 公式 10:

$$P_D = I^2 \times R \times 2 \text{ (multiplied by 2 because there are two channels)} \quad (7)$$

$$2 \times I^2 \times R = \frac{T_{J(MAX)} - T_A}{R_{\theta JA}} \quad (8)$$

$$T_A = T_{J(MAX)} - R_{\theta JA} \times 2 \times I^2 \times R \quad (9)$$

$$T_A = 125^\circ\text{C} - 62.5^\circ\text{C/W} \times 2 \times (4 \text{ A})^2 \times 27 \text{ m}\Omega = 71^\circ\text{C} \quad (10)$$

For  $V_{BIAS} = 5 \text{ V}$ ,  $V_{IN} = 5 \text{ V}$ , the maximum continuous current for an ambient temperature of 85°C with the same current flowing through each channel can be determined by using 公式 11 to 公式 13:

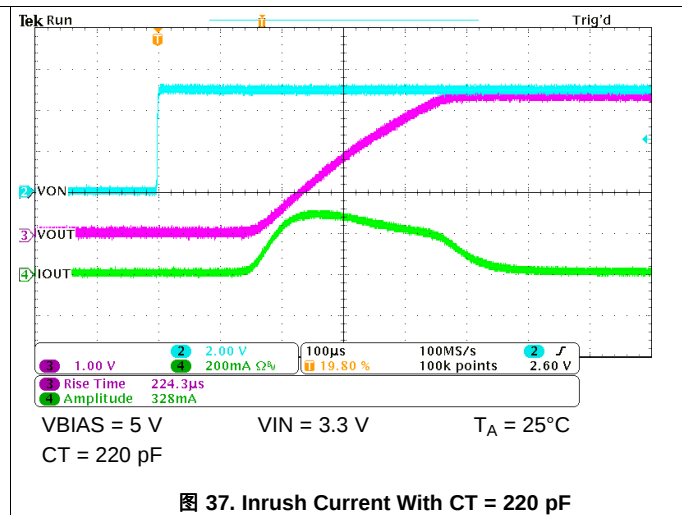
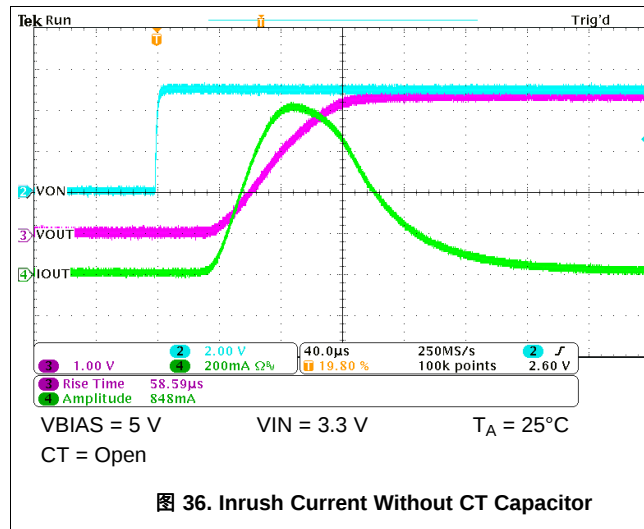
$$2 \times I^2 \times R = \frac{T_{J(MAX)} - T_A}{R_{\theta JA}} \quad (11)$$

$$I = \sqrt{\frac{T_{J(MAX)} - T_A}{2 \times R \times R_{\theta JA}}} \quad (12)$$

$$I = \sqrt{\frac{125^{\circ}\text{C} - 105^{\circ}\text{C}}{2 \times 27\text{m}\Omega \times 62.5^{\circ}\text{C/W}}} = 3.44 \text{ A per channel} \quad (13)$$

### 10.2.3 Application Curves

The twp scope captures show the usage of a CT capacitor in conjunction with the device. A higher CT value results in a slower rise and a lower inrush current.



## 11 Power Supply Recommendations

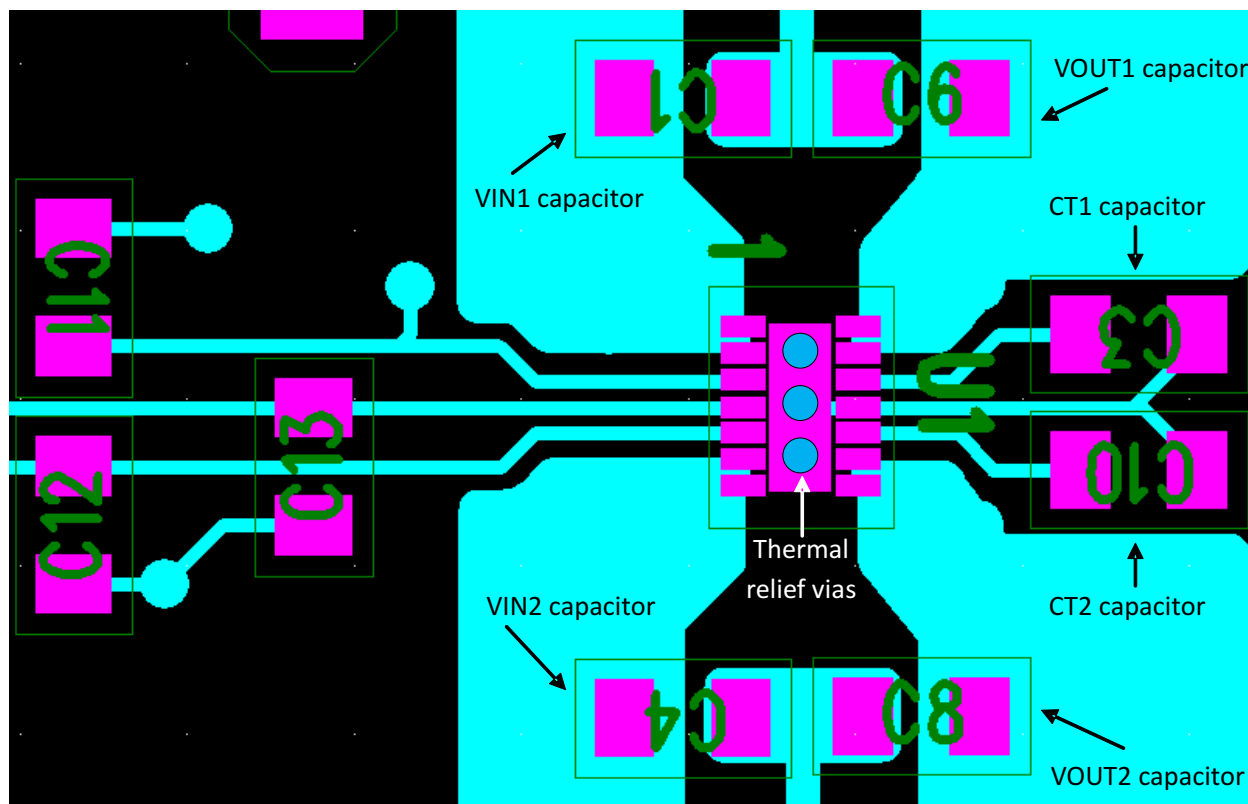
The device is designed to operate from a  $V_{BIAS}$  range of 2.5 V to 5.5 V and  $V_{IN}$  range of 0.8 V to 5.5 V. This supply must be well regulated and placed as close to the device pin as possible with the recommended 1- $\mu$ F bypass capacitor. If the supply is located more than a few inches from the device pins, additional bulk capacitance may be required in addition to the ceramic bypass capacitors. If additional bulk capacitance is required, an electrolytic, tantalum, or ceramic capacitor of 10  $\mu$ F may be sufficient.

## 12 Layout

### 12.1 Layout Guidelines

- VIN and VOUT traces must be as short and wide as possible to accommodate for high current.
- Use vias under the exposed thermal pad for thermal relief for high current operation.
- VINx pins must be bypassed to ground with low-ESR ceramic bypass capacitors. The typical recommended bypass capacitance is 1- $\mu$ F ceramic with X5R or X7R dielectric. This capacitor must be placed as close to the device pins as possible.
- VOUTx pins must be bypassed to ground with low-ESR ceramic bypass capacitors. The typical recommended bypass capacitance is one-tenth of the VINx bypass capacitor of X5R or X7R dielectric rating. This capacitor must be placed as close to the device pins as possible.
- The VBIAS pin must be bypassed to ground with low-ESR ceramic bypass capacitors. The typical recommended bypass capacitance is 0.1- $\mu$ F ceramic with X5R or X7R dielectric.
- The CTx capacitors must be placed as close to the device pins as possible. The typical recommended CTx capacitance is a capacitor of X5R or X7R dielectric rating with a rating of 25 V or higher.

### 12.2 Layout Example



## 13 器件和文档支持

### 13.1 器件支持

#### 13.1.1 开发支持

有关 TPS22968 和 TPS22968-Q1 PSpice 瞬态模型，请参阅 [SLVMA29](#)。

有关 TPS22968N 和 TPS22968N-Q1 PSpice 瞬态模型，请参阅 [SLVMA9](#)。

### 13.2 文档支持

#### 13.2.1 相关文档

请参阅如下相关文档：

- 《管理浪涌电流》，[SLVA670A](#)
- 《负载开关功耗之静态电流与关断电流》，[SLVA757](#)
- 《TPS22968EVM-007 双路 4A 负载开关》，[SLVUA30](#)
- 《负载开关热效应注意事项》，[SLVUA74](#)
- 《TPS22968/68N-Q1 双通道 5.5V 4A 27mΩ 负载开关 EVM 用户指南》，[SLVUAE2A](#)
- 《TPS22968NEVM 双路 4A 负载开关》，[SLVUAL0](#)

### 13.3 相关链接

下面的表格列出了快速访问链接。类别包括技术文档、支持与社区资源、工具和软件，以及申请样片或购买产品的快速链接。

表 4. 相关链接

| 器件        | 产品文件夹                 | 样片与购买                 | 技术文档                  | 工具和软件                 | 支持和社区                 |
|-----------|-----------------------|-----------------------|-----------------------|-----------------------|-----------------------|
| TPS22968  | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> |
| TPS22968N | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> | <a href="#">请单击此处</a> |

### 13.4 接收文档更新通知

如需接收文档更新通知，请访问 [ti.com](http://ti.com) 上的器件产品文件夹。请单击右上角的通知我 进行注册，即可收到任意产品信息更改每周摘要。有关更改的详细信息，请查看任意已修订文档中包含的修订历史记录。

### 13.5 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

## **13.8 Glossary**

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## **14 机械、封装和可订购信息**

以下页面包括机械、封装和可订购信息。这些信息是指定器件的最新可用数据。这些数据发生变化时，我们可能不会另行通知或修订此文档。如欲获取此产品说明书的浏览器版本，请参阅左侧的导航栏。

## PACKAGING INFORMATION

| Orderable part number         | Status<br>(1) | Material type<br>(2) | Package   Pins  | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|-------------------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">TPS22968DPUR</a>  | Active        | Production           | WSON (DPU)   14 | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 105   | RB968               |
| TPS22968DPUR.A                | Active        | Production           | WSON (DPU)   14 | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 105   | RB968               |
| <a href="#">TPS22968DPUT</a>  | Active        | Production           | WSON (DPU)   14 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 105   | RB968               |
| TPS22968DPUT.A                | Active        | Production           | WSON (DPU)   14 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 105   | RB968               |
| TPS22968DPUTG4                | Active        | Production           | WSON (DPU)   14 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 105   | RB968               |
| TPS22968DPUTG4.A              | Active        | Production           | WSON (DPU)   14 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-2-260C-1 YEAR               | -40 to 105   | RB968               |
| <a href="#">TPS22968NDPUR</a> | Active        | Production           | WSON (DPU)   14 | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 105   | RB968N              |
| TPS22968NDPUR.A               | Active        | Production           | WSON (DPU)   14 | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 105   | RB968N              |
| <a href="#">TPS22968NDPUT</a> | Active        | Production           | WSON (DPU)   14 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 105   | RB968N              |
| TPS22968NDPUT.A               | Active        | Production           | WSON (DPU)   14 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 105   | RB968N              |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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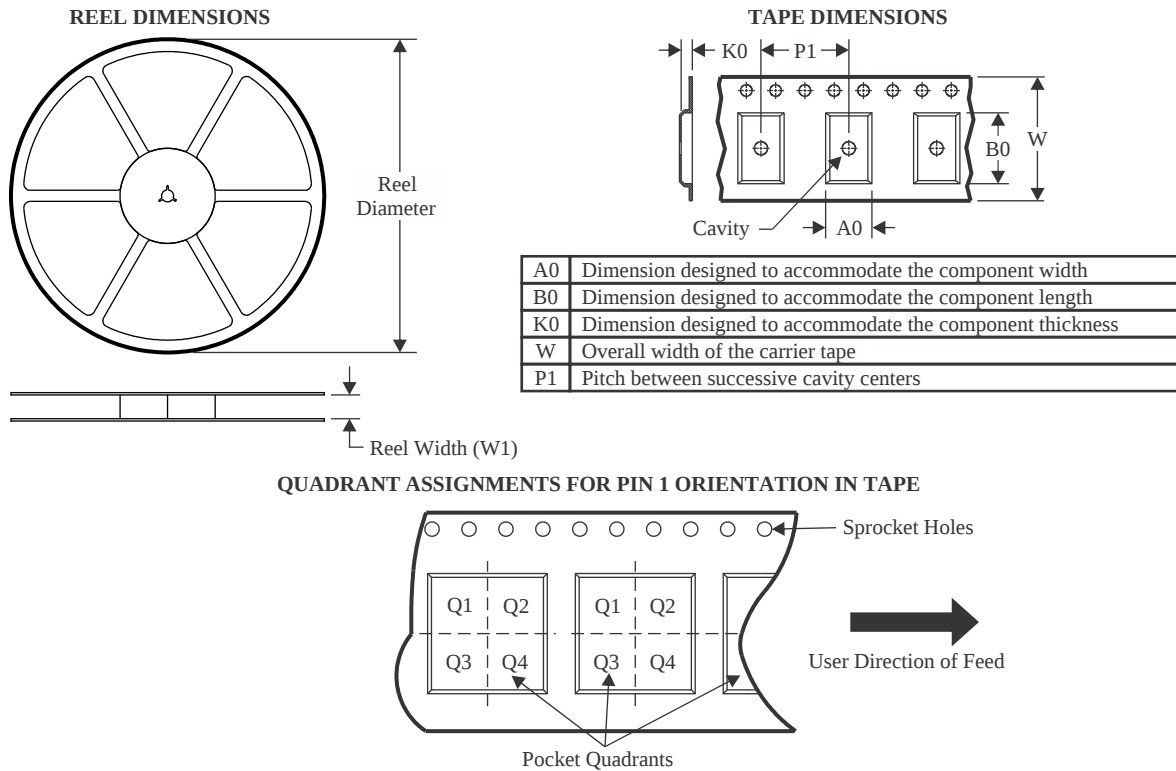
**OTHER QUALIFIED VERSIONS OF TPS22968 :**

- Automotive : [TPS22968-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS22968DPUR   | WSO          | DPU             | 14   | 3000 | 180.0              | 8.4                | 2.25    | 3.25    | 1.05    | 4.0     | 8.0    | Q1            |
| TPS22968DPUR   | WSO          | DPU             | 14   | 3000 | 180.0              | 8.4                | 2.25    | 3.25    | 1.05    | 4.0     | 8.0    | Q1            |
| TPS22968DPUT   | WSO          | DPU             | 14   | 250  | 180.0              | 8.4                | 2.25    | 3.25    | 1.05    | 4.0     | 8.0    | Q1            |
| TPS22968DPUTG4 | WSO          | DPU             | 14   | 250  | 180.0              | 8.4                | 2.25    | 3.25    | 1.05    | 4.0     | 8.0    | Q1            |
| TPS22968NDPUR  | WSO          | DPU             | 14   | 3000 | 180.0              | 8.4                | 2.25    | 3.25    | 1.05    | 4.0     | 8.0    | Q1            |
| TPS22968NDPUT  | WSO          | DPU             | 14   | 250  | 180.0              | 8.4                | 2.25    | 3.25    | 1.05    | 4.0     | 8.0    | Q1            |

## TAPE AND REEL BOX DIMENSIONS



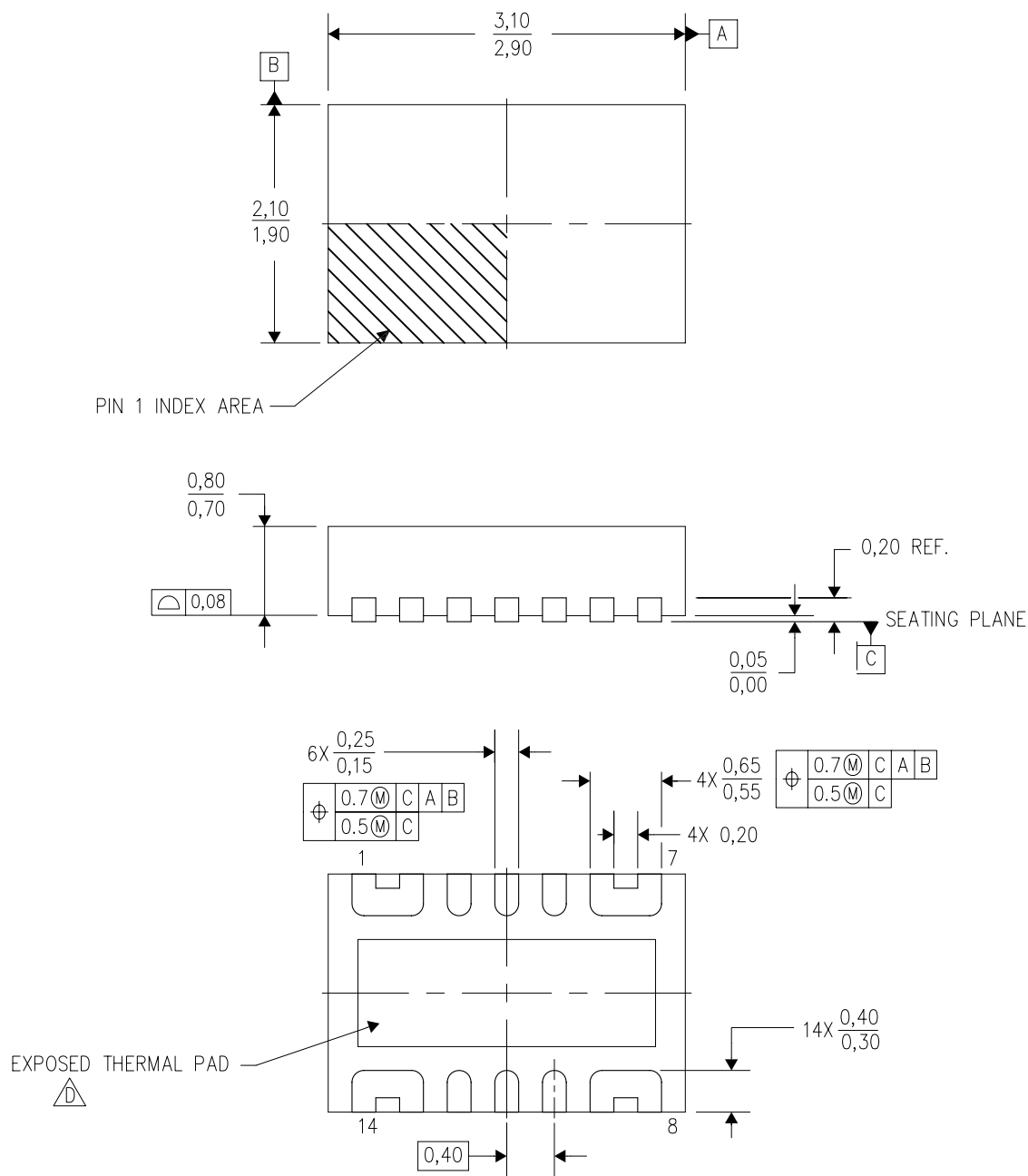
\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS22968DPUR   | WSN          | DPU             | 14   | 3000 | 210.0       | 185.0      | 35.0        |
| TPS22968DPUR   | WSN          | DPU             | 14   | 3000 | 210.0       | 185.0      | 35.0        |
| TPS22968DPUT   | WSN          | DPU             | 14   | 250  | 210.0       | 185.0      | 35.0        |
| TPS22968DPUTG4 | WSN          | DPU             | 14   | 250  | 210.0       | 185.0      | 35.0        |
| TPS22968NDPUR  | WSN          | DPU             | 14   | 3000 | 182.0       | 182.0      | 20.0        |
| TPS22968NDPUT  | WSN          | DPU             | 14   | 250  | 182.0       | 182.0      | 20.0        |

## MECHANICAL DATA

DPU (R-PWSON-N14)

PLASTIC SMALL OUTLINE NO-LEAD



4211321/B 11/10

NOTES:

|           |                                                                                               |
|-----------|-----------------------------------------------------------------------------------------------|
| A.        | All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.  |
| B.        | This drawing is subject to change without notice.                                             |
| C.        | Small Outline No-Lead (SON) package configuration.                                            |
| <b>D.</b> | The package thermal pad must be soldered to the board for thermal and mechanical performance. |
|           | See the Product Data Sheet for details regarding the exposed thermal pad dimensions.          |
| E.        | This package is Pb-free.                                                                      |

DPU (R-PWSON-N14)

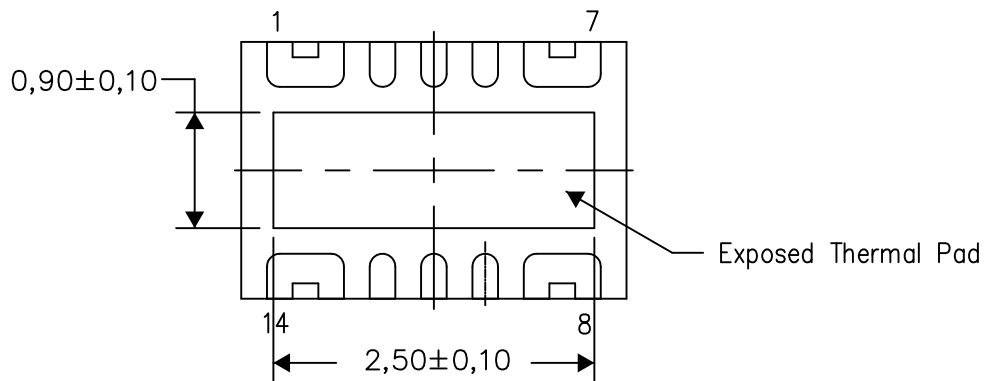
PLASTIC SMALL OUTLINE NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

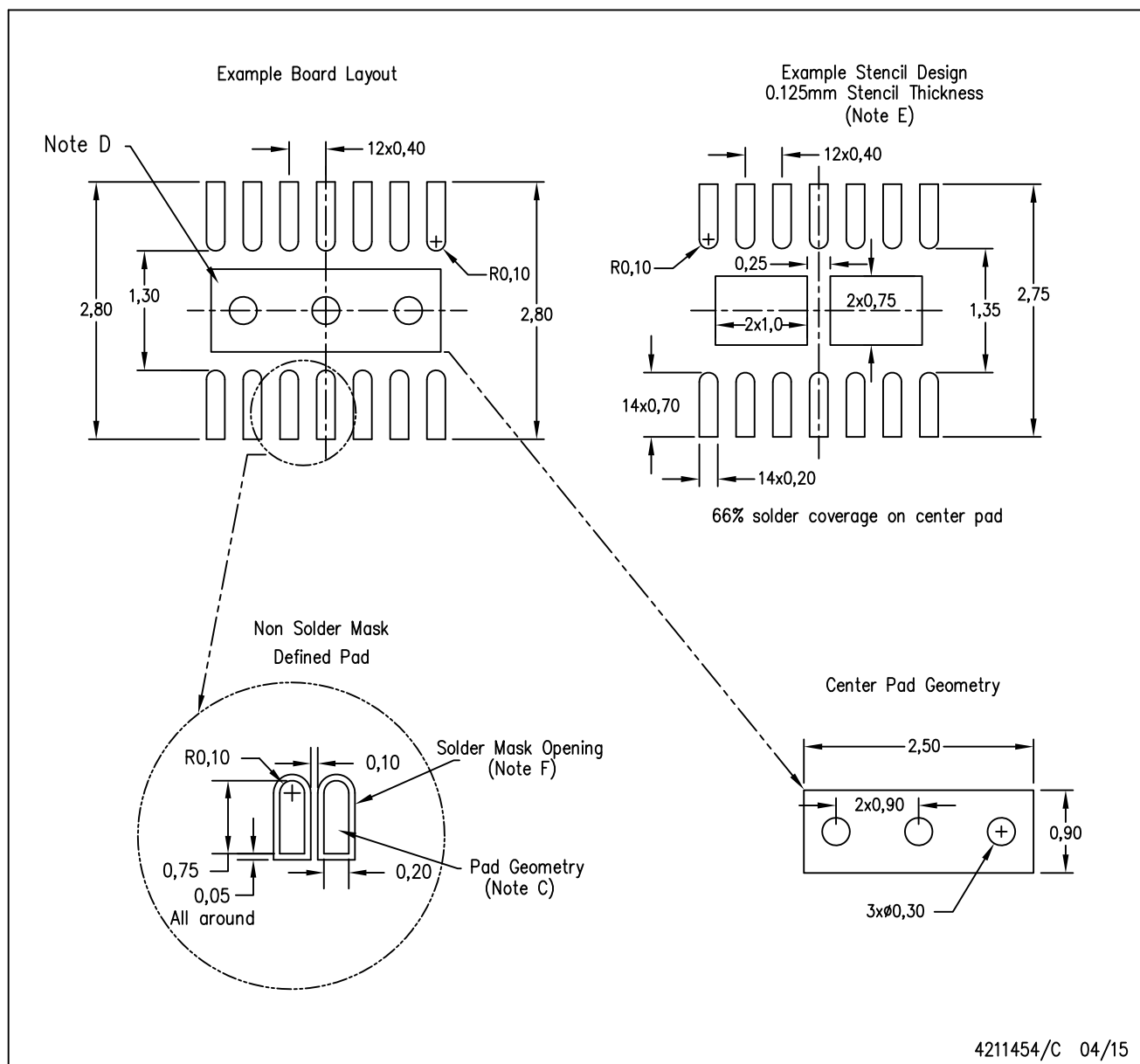
Exposed Thermal Pad Dimensions

4211395/C 04/15

NOTE: All linear dimensions are in millimeters

DPU (R-PWSON-N14)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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